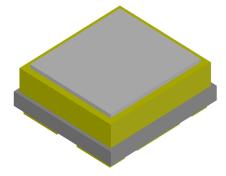
JSFON



OC-VC series

Product Specification

Product	3532 VCSEL Emitter
Part Number	OCVC32-1290V8530-V0
Issue Date	2019/10/14



Features

- Vertical Cavity Surface Emitting Laser technology
- Package size = 3.5mm x 3.2mm x 1.3mm
- Pulse Output power 3W emitter
- Peak wavelength λ_p =850nm
- Divergence angles = 110°x90°
- Wavelength stabilized (0.07nm per °C)
- Narrow spectral width (<1nm)
- RoHS
- Photo Diode inside

Applications

- 3D depth sensing
- Gesture sensing
- Flood illuminator



Product Nomenclature

The product name is designated as below:

VCAB – CDEFGHIJK

Designation:

Notes

Designation	
AB = Package CDEF = Diver G = Internal C HI = Waveleng	gence Angle (2) ode
Notes	
1. Package	Size:
Symbol	Description
32	3.5mm x 3.2mm

2. Divergence Angle:

3. Wavelength:

Symbol	Description
85	850nm
94	940nm

4. Pulse mode Output Power:

Symbol	Description
05	0.5W
10	1W
20	2W
30	3W
40	4W



Maximum Ratings (Ta = 25 °C)

Parameter	Symbol	Values	Unit
Operating temperature range	T _{op}	-20 ~ 85	°C
Storage temperature range	T _{stg}	-40 ~ 85	°C
Maximum package SMT solder Reflow temperature		260°C 10seconds	°C

Characteristics(Ta = 25 °C)

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Pulse Output power	Po	I _F = 4.0 A	2400	3000	-	mW
Wavelength	λ_{p}	I _F = 4.0 A	840	850	860	nm
Forward Voltage	Vf	I _F = 4.0 A	1.8	2.1	2.4	V
Threshold current	l _{th}		-	500	-	mA
Power Conversion Efficiency	PCE	I _F = 4.0 A	-	33	-	%
Wave Shift	∆λ∕∆T	I _F = 4.0 A	-	0.07	-	nm/°C
Slope Efficiency			-	0.86	-	W/A

Note:

- Forward Voltage tolerance is ±0.1 V, Radiant Intensity tolerance is ±10% Others measurement allowance is ±10%.
- 2. VCSEL is mounted on PCB and measured with operating bias current @ 4A,10ms
- 3. Due to the special conditions of the manufacturing processes of VCSEL, the typical data of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.

Photodiode Electrical / Optical Characteristics(Ta = 25 °C)

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Forward Voltage	Vf	I _F = 10 mA	0.5		1.3	V
Reverse Breakdown Voltage	V_{BR}	I _R = 100 uA	35			V
Reverse Dark Current	I _D	V _R = 10 V		2	10	nA
Light Current	ΙL	$V_R = 5 V$		0.5		uA
Peak Sensing Wavelength	λ_{p}			850		nm



Radiometric Power Bin Structure at 4000mA

The flux bin of the proc	2400 ance of $\pm 10\%$ on flux and power meas duct may be modified for improvement	
The flux bin of the proc	•	
<u>Peak Wavele</u>	ength Bin Structure a	at 4000mA
Color Bin Code	Centroid Wavelength	
nfrared 850 85	850	

Forward Voltage Bin Structure at 4000mA

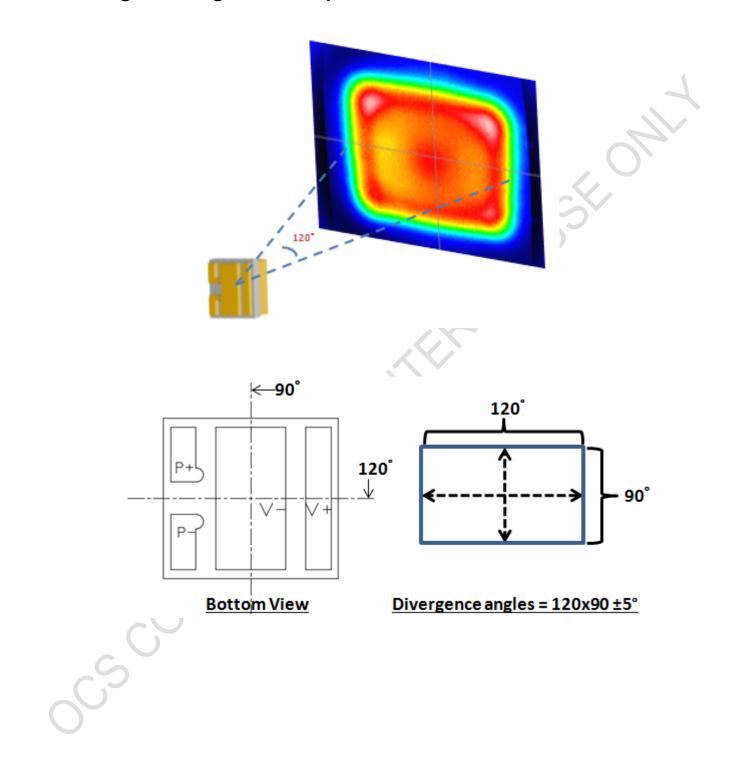
Color	Bin Code	Typical Voltage (V)	Maximum Voltage (V)
Infrared 850	A2	2.1	2.4

• OCS maintain a tolerance of ±0.1V for Voltage measurements.

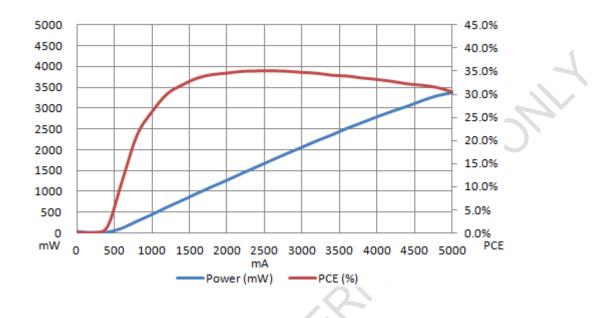
Sconfill



Divergence angles corresponds to the direction

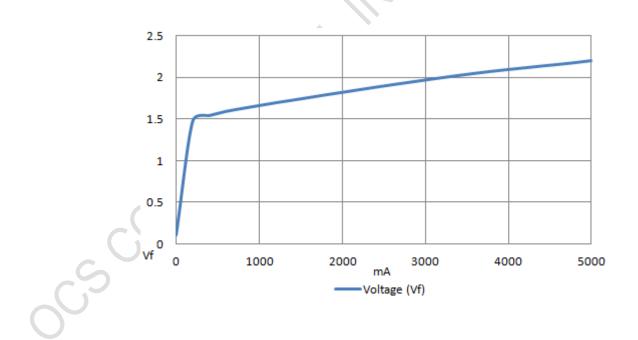






Pulse Output Power vs. Forward Current

Forward Voltage vs. Forward Current

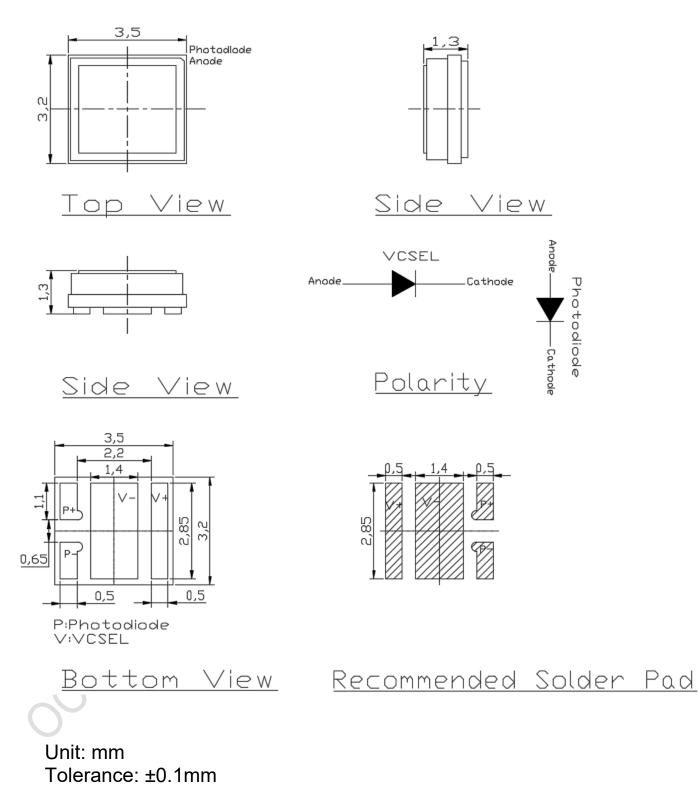


5



829

■ Outline Dimension





Cleaning

- 1. If washing is required, recommend to use alcohol as a solvent.
- 2. Recommend to avoid cleaning the VCSEL by ultrasonic. If necessary, pre-test the VCSEL is necessary to confirm whether any damage occur after the process.

Precautions for use

1. Over-current-proof

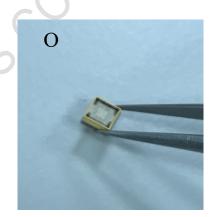
1.1 Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen).

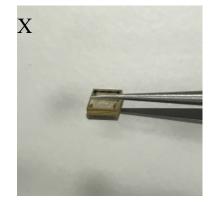
2. Storage

- 2.1 Do not open moisture proof bag before the products are ready to use.
- 2.2 Before opening the package: The VCSEL should be kept at 30°C or less and 90%RH or less.
- 2.3 After opening the package: The VCSEL floor life is 1 year under 30°C or less and 60% RH or less. If unused VCSEL remain, it should be stored in moisture proof packages.
- 2.4 If the moisture absorbent material (silica gel) has faded away or the VCSEL have exceeded the storage time, baking treatment should be performed using the following conditions. Baking treatment: 60±5°C for 24 hours.

3. Handling indications

3.1 During processing, mechanical stress on the surface should be minimized as much as possible. Sharp objects of all types should not be used to pierce the sealing compound. In general, VCSEL should only be handled at the housing. This also applies to VCSEL without a diffuser, since the surface can also become scratched.

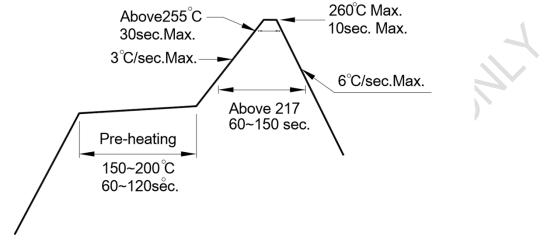






4. Soldering Condition

4.1 Pb-free solder temperature profile (JEDEC-STD-020 latest version compliant)



- 4.2 Reflow soldering should not be done more than two times.
- 4.3 When soldering, do not put stress on the VCSEL during heating.
- 4.4 After soldering, do not warp the circuit board.

5. Soldering Iron

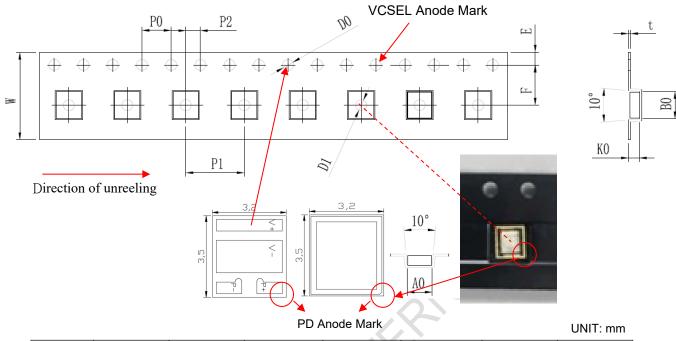
5.1 Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

6. Repairing

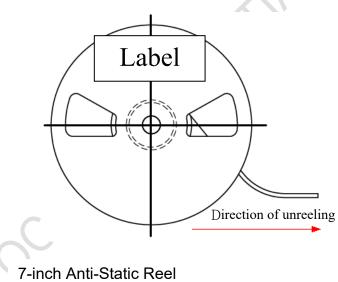
6.1 Repair should not be done after the VCSEL have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the VCSEL will or will not be damaged by repairing.



Carrier Taping



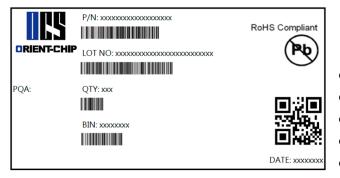
symbol	Ao	Bo	Ko	Po	P1	P2	Т
spec	3.45±0.10	3.75±0.10	1.50±0.10	4.00±0.10	8.00±0.10	2.00±0.10	0.30±0.05
symbol	E	F	Do	D1	W	10Po	
spec	1.75±0.10	5.50±0.10	1.50+0.10-	1.50±0.10-	12.00±0.30	40.0±0.10	
			0.0	0.0			



Max 500pcs/reel



Product Labeling



- P/N: OCS Product Model Name
- LOT: Lot Number
- QTY: Q'ty
- BIN: mW/nm/Vf (ex.[A1/94/V1])
- DATE: Enter the warehouse

Moisture Resistant Packing

